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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Complete If Known		
		Application Number	10/990,004 10/811,581	
		Filing Date	March 4, 2002	
		First Named Inventor	Man Hon Cheng	
		Group Art Unit	2827	
Examiner Name	Guan G. Hui Jasmine Clark			
Sheet		of	Attorney Docket Number	SC11852HP

U. S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number -Kind Code ² (if known)			
jbe	AA	5,122,860	06/16/1992	Kikuchi <i>et al.</i>	
	AB	6,265,530 B1	07/24/2001	Herr <i>et al.</i>	
	AC	2001/0012680 A1	08/09/2001	Cobbley <i>et al.</i>	
	AD	2002/0182774 A1	12/05/2002	Heckman	

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Foreign Patent Document		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Country Code ³	Number ⁴ Kind Code ² (if known)			

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
jbe	AE	National Semiconductor Corporation, "Semiconductor Packaging Assembly Technology", August 1999, pp. 1-8.	
	AF	National Semiconductor Corporation, "Plastic Package Moisture-Induced Cracking", August 1999, pp. 1-5.	
jbe	AG	Han <i>et al.</i> , "Three-Dimensional Simulation of Microchip Encapsulation Process", Dept. of Mechanical Engineering-Engineering Mechanics, Michigan Technological University, Houghton, Michigan 49931, pp. 1-17 and Figs. 1-11.	

Examiner Signature	Jasmine Clark	Date Considered	12/08/04
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¹ Unique citation designation number. ² See Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English Language Translation is attached.

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